Docket No.: JCLA8533-D2 Date: January 09, 2004

COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VA 22313-1450

ATTENTION: APPLICATION BRANCH

Sir:

This is a request for filing a continuation application under 37 CFR 1.53 (b) as a divisional application of prior application No.10/055,568 filed on January 22, 2002.

Prior application information: Examiner: MITCHELL, JAMES M. ; Group Art Unit: 2827

The entire disclosure of the prior application, from which an oath or declaration is supplied herewith as indicated below, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference.

Transmitted herewith for filing is the patent application of

Inventor(s): MOU-SHIUNG LIN;

JIN-YUAN LEE;

CHING-CHENG HUENG;

For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

Enclosed are:

- (X) Specification in FOURTY-ONE (41) pages.
- (X) SIXTEEN (16) sheets of Drawings.
- (X) Preliminary Amendment.
- (X) A copy of Declaration and Power of Attorney from the prior application is enclosed.
- (X) Applicant claims small entity status. See 37 CFR 1.27.
- (X) Return prepaid postcard.

CLAIMS AS FILED			
NUMBER FILED	NUMBER EXTRA	RATE	FEE
		\$ 385	\$ 385
27 - 20 =	7 ×	\$9	\$ 63
1 - 3 =	0 ×	\$ 43	\$ 0
If application contains any multiple dependent claims(s), then add		\$ 145	\$ 0
TOTAL FILING FEE		\$ 448	
	NUMBER FILED 27 - 20 = 1 - 3 = nultiple dependent claims	NUMBER FILED EXTRA 27 - 20 = 7 × 1 - 3 = 0 × nultiple dependent claims(s), then add	NUMBER FILED NUMBER EXTRA RATE \$ 385 \$ 385 27 - 20 = 7 × \$ 9 1 - 3 = 0 × \$ 43 nultiple dependent claims(s), then add \$ 145

- (X) A check in the amount of \$ 448 to cover the filing fee is enclosed.
- (X) The commissioner is authorized to charge any additional necessary fee to Account No. 50-0710 (Order No. JCLA8533-D2). A duplicate copy of this sheet is enclosed.

Corresp ndence addr ss:

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Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No.

: JCLA8533-D2

Inventor(s)

: MOU-SHIUNG LIN;

JIN-YUAN LEE:

CHING-CHENG HUENG:

For

: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON

SUBSTRATE AND METHOD OF MANUFACTURING THE

SAME

"Express Mail"

Mailing Label No.

: EV 300987573 US

Date of Deposit

: January 09, 2004

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in <u>41</u> page(s); <u>16</u> sheets of drawing(s); Copy of Declaration and Power of Attorney from prior application; Preliminary Amendment; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Commissioner for Patents, P.O. BOX 1450, Alexandria, VA 22313-1450

Michelle Chang